202-955-5771

Form PTO-1595 (Rev OMB No. 0651-0027 (i		U.S. DEPARTMENT OF COMMERCI United States Patent and Trademark Offic
,	RECORDATION FOR	M COVER SHEET
	PATENTS	SONLY
To the Director o	the U.S. Patent and Trademark Office: Please	record the attached documents or the new address(es) below.
1. Name of cor	veying party(les)/Execution Date(s):	2. Name and address of receiving party(ies)
Minoru Shimiz	u	Name: Sony Computer Entertainment Inc.
		Internal Address:
Execution Date(s	: March 18, 2005	Street Address:
Additional name(s) of	conveying party(ies) attached? Yes X No	
3. Nature of Con	veyance:	2-6-21, Minami-Aoyama, Minato-ku
Assignment	Merger	
Security Agre	ement Change of Name	City: Tokyo
Government	nterest Assignment	State:
	er 9424, Confirmatory License	
		Country: JAPAN Zip: 107-0062 Additional name(s) & address(es)
:	ase correct DOC DATE: n's error	attached:
	m: 3/09/2005	Yes x No
	3/18/2005	
4. Application of	patent number(s):	his document is being filed together with a new application.
A. Patent Applica	tion No.(s)	B. Patent No.(s)
29/22	4,853	
	Additional numbers attached?	Yes X No
	ss to whom correspondence iment should be mailed:	6. Total number of applications and patents involved:
^{Name:} RA	DER, FISHMAN & GRAUER PLLC	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
internal Address: A	ktty. Dkt.: NAK-0263	Authorized to be charged by credit card
	233 20th Street, N.W.	
s	uite 501	
		Enclosed
i		None required (government interest not affecting title)
City:	Washington	8. Payment Information
State:	DC zlp: 20036	a. Credit Card Last 4 Numbers
Phone Number:	(202) 955-3750	Expiration Date
Fax Number:	(202) 955-3751	b. Deposit Account Number 18-0013
Email Address:		Authorized User Name <u>Toshikatsu Imaizumi</u>
9. Signature:		
	Z. Grann	December 28, 2005
	Signature	Date
	Toshikatsu Imaizumi - L0046 Name of Person Signing	Total number of pages including cover sheet, attachments, and documents:
	ivanie or reison agining	- 17

PATENT REEL: 017143 FRAME: 0988

PATENT

REEL: 017143 FRAME: 0989

Docket Number: NAK-0263

ASSIGNMENT

whereas, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

ELECTRIC CONNECTOR

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Computer Entertainment Inc. a Japanese comporation with offices at 2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062, JAPAN, (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of Ten Dollar (\$10.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assigh, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all $\hat{\mathbf{L}}$ etters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

PATENT REEL: 017143 FRAME: 0990 And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 29/224,853

, Filing Date: March 9, 2005

This assignment executed on the dates indicated below.

Minoru SHIMIZU	Ininoru Se	himizu Max	18, 2005
	Signature	Date	
	Signature	Date	
	Signature	Date	
: }	Signature	Date	

PATENT REEL: 017143 FRAME: 0991

RECORDED: 12/28/2005